

IC SOCKETS- DUAL WIPE

LOW PROFILE I.C. SOCKET 2.54MM PITCH

Part Number	Pins	A	B	C	D
MH06	6	7.62	4.98	9.88	7.62
MH08	8	10.16	7.62	9.88	7.62
MH14	14	17.76	15.24	9.88	7.62
MH16	16	20.32	17.78	9.88	7.62
MH18	18	22.86	20.32	9.88	7.62
MH20	20	24.40	22.86	9.88	7.62
MH22	22	27.84	25.40	12.42	10.16
MH24	24	30.48	33.02	17.50	15.24
MH28	28	35.56	48.26	17.50	15.24
MH40	40	50.8	48.26	17.50	15.24
MH48	48	60.9	58.36	17.50	15.24
MH22SKIN	22	27.84	25.40	9.88	7.62
MH24SKIN	24	30.48	33.02	9.88	7.62
MH28SKIN	28	35.56	48.26	9.88	7.62

FEATURES

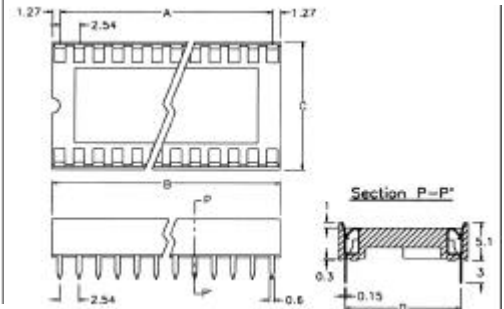
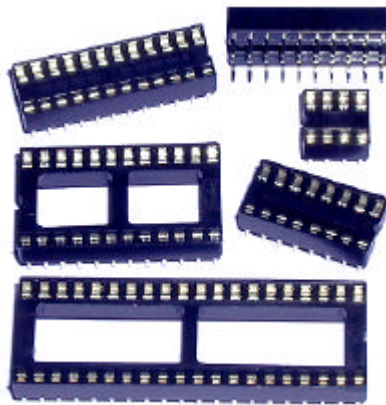
- Compact size for high-density packaging
- Polarized body design assures proper package alignment
- Fast and easy package installation
- The contact design also solder wicking
- The ventilated molding with stand-off allow easy removal of flux residue left after assembly operations

MATERIAL

Insulator: PBT + 30% glass fiber (UL94V-0)
Contact: Phosphor bronze/brass
Contact Plated: Gold over nickel or tin
Colour: Black

SPECIFICATION

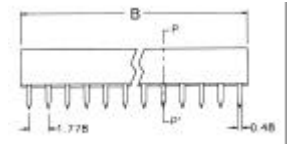
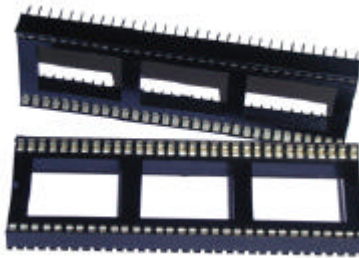
Current Rate: 1A
Dielectric Strength: 500V for one minute
Insulator Resistance: 1000 M Ω min at 250V DC
Temperature: -55°C - +105°C



HIGH DENSITY I.C. SOCKET 1.778MM PITCH

Dual wipe low profile sockets featuring 0.07" (1.778mm) lead spacing.

Part Number	Pins	A	B	C	D
MH24SHRINK	24	19.56	21.3	12.65	10.16
MH28SHRINK	28	23.11	25.17	12.65	10.16
MH64SHRINK	64	55.12	57.0	21.54	19.05



IC SOCKETS- MACHINED PIN

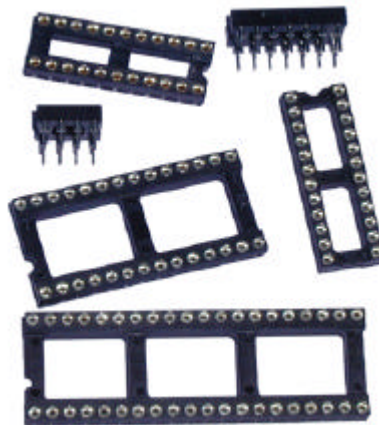
LOW PROFILE MACHINED I.C. SOCKETS

Four finger beryllium copper contact meets high vibration and shock requirements

FEATURES

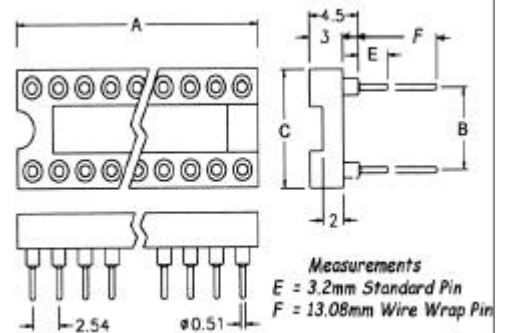
- Funnel shaped four-fingered contacts provide easy IC insertion, high reliability
 - Precision Swiss machined sockets are field-proven for min. of 1,000 cycles
 - Fit standard DIP with 2.54mm x 2.54mm pin spacing
 - Low profile for max packaging density
 - Closed bottom sleeve protects against solder wicking
 - Short contact legs assure contact with shortlegged IC's
- Available in Solder Pin or Wire Wrap

Standard Part Number	Wire Wrap Part Number	Pins	A	B	C
BU-060Z	BU-063Z	6	7.60	7.62	10.10
BU-080Z	BU-083Z	8	10.10	7.62	10.10
BU-140Z	BU-143Z	14	17.70	7.62	10.10
BU-160Z	BU-163Z	16	20.32	7.62	10.10
BU-180Z	BU-183Z	18	22.80	7.62	10.10
BU-200Z	BU-203Z	20	25.30	7.62	10.10
BU-220Z	BU-223Z	22	27.80	10.16	12.60
BU-240Z	BU-243Z	24	30.40	15.24	17.70
BU-240ZSK	BU-243ZSK	24	30.40	10.16	12.60
BU-280Z	BU-283Z	28	35.50	15.24	17.70
BU-280ZSK	BU-283ZSK	28	35.50	10.16	12.60
BU-400Z	BU-403Z	40	50.60	15.24	17.70
BU-480Z	BU-483Z	48	60.90	15.24	17.70
BU-640Z	BU-643Z	64	81.10	22.86	25.30



SPECIFICATION

Current Rate: 1A/Pin
Innercontact Material: Beryllium copper, 4 or 6 fingers (std 6 fingers)
Contact Plating: Gold or tin over nickel
Sleeve Material: Brass CA Alloy 360
Sleeve Plating: Tin in gold
Depth of Insertion: 2.3-3.7mm
Frequency of Insertion: 1,000 cycles min.
Vibration Rating: 20 g per MIL-STD-202
Shock Rating: 150 g per MIL-STD-202
Insulator Material: Polyester, UL 94V-0
Temperature: -65°C - +150°C



HIGH DENSITY I.C. SOCKET 1.778MM PITCH

High density Dual in line sockets for devices featuring 0.07" (1.778mm) lead spacing. Four finger beryllium copper contact meets high vibration and shock requirements.

Part Number	Pins	A	B	C
BU24SHRINK	24	21.55	15.24	17.64
BU28SHRINK	28	25.2	15.24	17.78
BU64SHRINK	64	57.4	19.05	21.59

